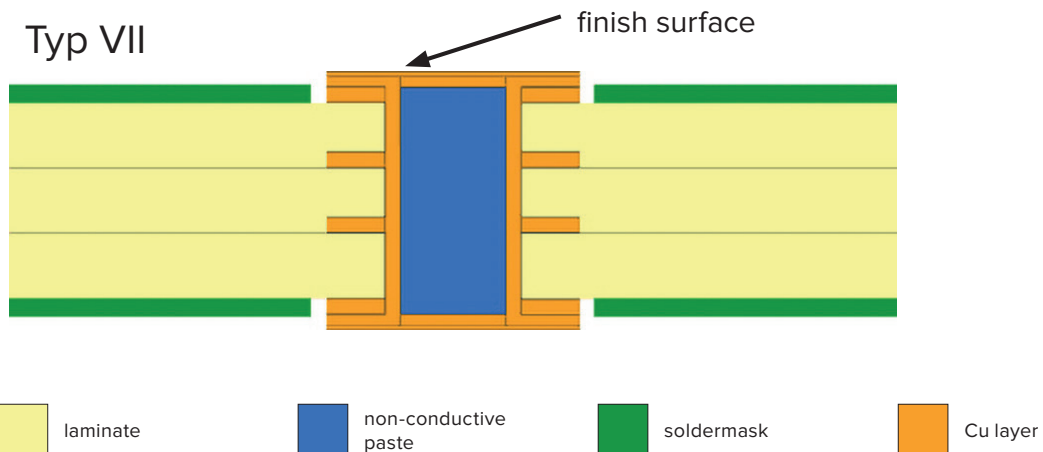


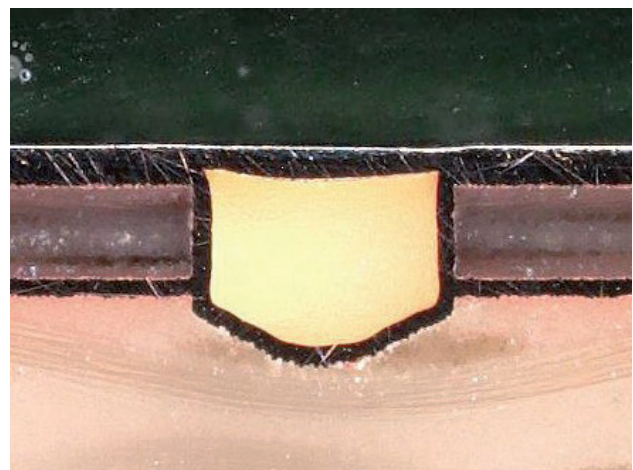
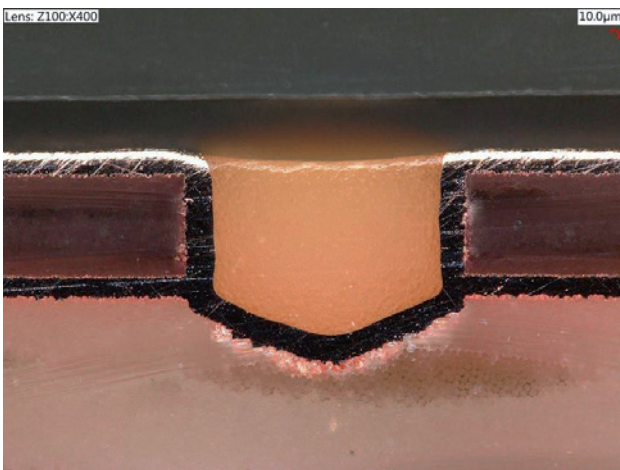
Via filling

Non-conductive paste filling

We are using doublehead technology form I.T.C. Technology is making vacuum between heads, so we can fill even blind vias. We can make filling IPC 4761 type VII (plated with Cu and finish surface). This type is suitable for via-in-pad.



If not specified we are filling all VIA's up to 0,45mm drilling diameter. Best option is to specify maximum size of the PTH you want to fill with epoxy paste. Or specify exact diameter you need to filled. If you need to fill only selected holes or selected area, this must be specified in production data or on separate drawing.



Non-conductive paste

Minimal plated hole	min. 0,1 mm
Maximum plated hole	max. 2,0 mm
Aspect ratio for PTH	max. 40:1
Aspect ratio blind hole	max. 1:1
IPC-4761 type	VII
PCB thickness	0,4–3,2 mm

Plugged via has to be at least 5 mm from the edge of board (maximum board size 265 x 455 mm).

More about TAYIO paste: <https://www.gatema.com/file-link/filling-paste-tds-thp-100dx1.pdf>